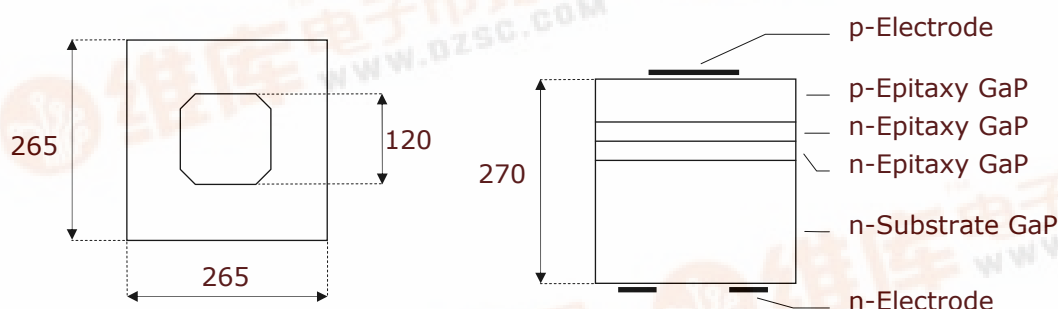


PURE-GREEN **Item No.: 161210**

1. This specification applies to GaP / GaP LED Chips
2. Structure
 - 2.1 Mesa structure
 - 2.2 Electrodes

| | |
|------------------|----------|
| p-side (anode) | Au alloy |
| n-side (cathode) | Au alloy |
3. Outlines (dimensions in microns)



Wire bond contacts can also be circular or square

4. Electrical and optical characteristics (T=25°C)

| Parameter | Symbol | Conditions | min | typ | max | Unit |
|----------------------|-------------|-----------------------|-----|------|------|---------------|
| Forward voltage | V_F | $I_F = 20 \text{ mA}$ | | 2,30 | 2,60 | V |
| Reverse current | I_R | $V_R = 5 \text{ V}$ | | | 10 | μA |
| Luminous intensity * | I_V | $I_F = 20 \text{ mA}$ | 1,4 | 2,0 | | mcd |
| Peak wavelength | λ_P | $I_F = 20 \text{ mA}$ | | 557 | | nm |

* On request, wafers will be delivered according to luminous intensity classes
Brightness measurement at OSA on gold plate

5. Packing

Dice on adhesive film with 1) wire bond side on top
2) back contact on top

6. Labeling

| | | | |
|------|---------|--------------------|----------|
| Type | Lot No. | I _v typ | Quantity |
| | | min | |
| | | max | |

